OptiMOS™-T2 Power-Transistor

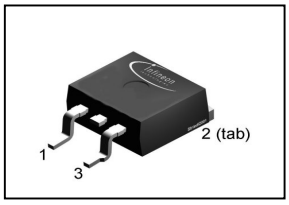
Features

- N-channel - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green package (lead free)
- 100% Avalanche tested

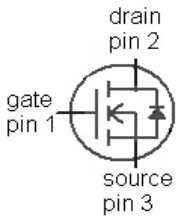
Product Summary

V_{DS}	40	V
$R_{DS(on),max}$	3.6	mΩ
I_D	120	A

PG-TO263-3-2



Type	Package	Ordering Code	Marking
IPB120N04S4-04	PG-TO263-3-2	-	4N0404



Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	T_C=25°C, V_{GS}=10V	120	A
		T_C=100°C, V_{GS}=10V[1)]	91	
Pulsed drain current[1)]	$I_{D,pulse}$	T_C=25°C	480	
Avalanche energy, single pulse	E_{AS}	I_D=60A	75	mJ
Avalanche current, single pulse	I_{AS}	-	120	A
Gate source voltage	V_{GS}	-	±20	V
Power dissipation	P_{tot}	T_C=25°C	79	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1		-	55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics[1]						
Thermal resistance, junction - case	R_{thJC}		-	-	1.9	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}		-	-	62	
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm^2 cooling area[2]	-	-	40	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D= 1mA	40	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=40µA	2.0	3.0	4.0	
Zero gate voltage drain current	I_{DSS}	V_{DS}=40V, V_{GS}=0V, T_j=25°C	-	0.01	1	µA
		V_{DS}=18V, V_{GS}=0V, T_j=85 °C[2]	-	3	36	
Gate-source leakage current	I_{GSS}	V_{GS}=20V, V_{DS}=0V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=100A	-	3.2	3.6	mΩ

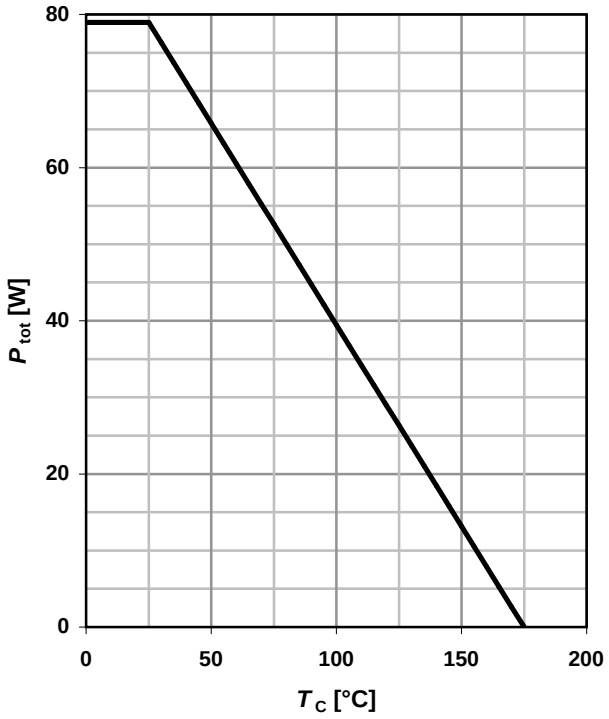
Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics[1]						
Input capacitance	C_{iss}	V_{GS}=0V, V_{DS}=25V, f=1MHz	-	3150	4100	pF
Output capacitance	C_{oss}		-	770	1000	
Reverse transfer capacitance	C_{rss}		-	30	70	
Turn-on delay time	$t_{d(on)}$	V_{DD}=20V, V_{GS}=10V, I_D=120A, R_G=3.5Ω	-	11	-	ns
Rise time	t_r		-	18	-	
Turn-off delay time	$t_{d(off)}$		-	9	-	
Fall time	t_f		-	15	-	
Gate Charge Characteristics[1]						
Gate to source charge	Q_{gs}	V_{DD}=32V, I_D=120A, V_{GS}=0 to 10V	-	20	26	nC
Gate to drain charge	Q_{gd}		-	7	16	
Gate charge total	Q_g		-	42	55	
Gate plateau voltage	$V_{plateau}$		-	6.0	-	V
Reverse Diode						
Diode continous forward current[1]	I_S	T_C=25°C	-	-	120	A
Diode pulse current[1]	$I_{S,pulse}$		-	-	480	
Diode forward voltage	V_{SD}	V_{GS}=0V, I_F=100A, T_j=25°C	-	0.9	1.3	V
Reverse recovery time[1]	t_{rr}	V_R=20V, I_F=I_S, di_F/dt=100A/µs	-	45	-	ns
Reverse recovery charge[1]	Q_{rr}		-	50	-	nC

[1] Defined by design. Not subject to production test.

[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

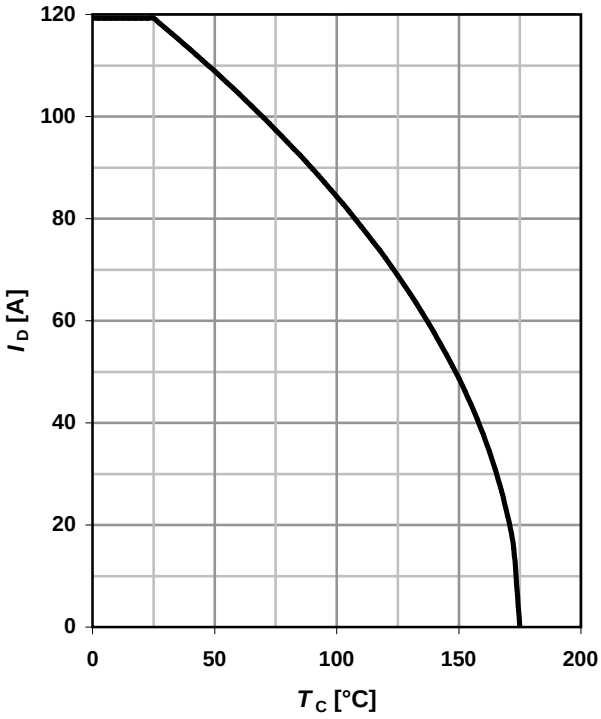
1 Power dissipation

$P_{tot} = f(T_C)$; $V_{GS} \geq 6$ V



2 Drain current

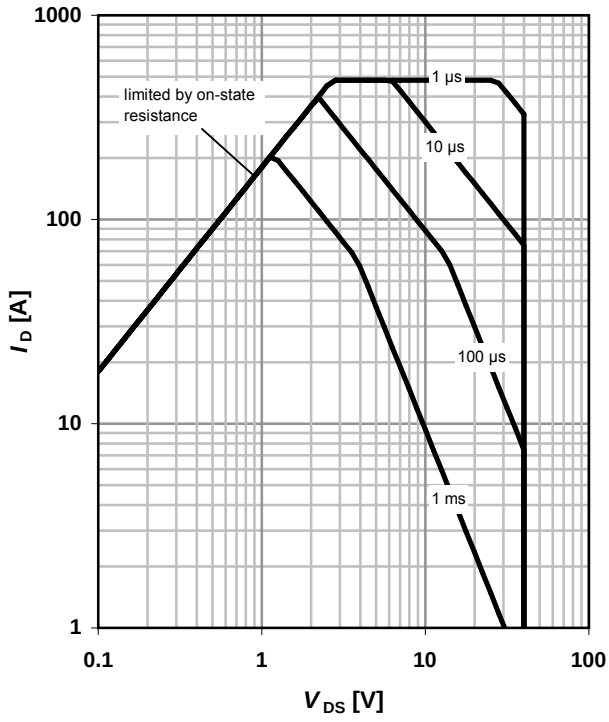
$I_D = f(T_C)$; $V_{GS} \geq 6$ V



3 Safe operating area

$I_D = f(V_{DS})$; $T_C = 25$ °C; $D = 0$

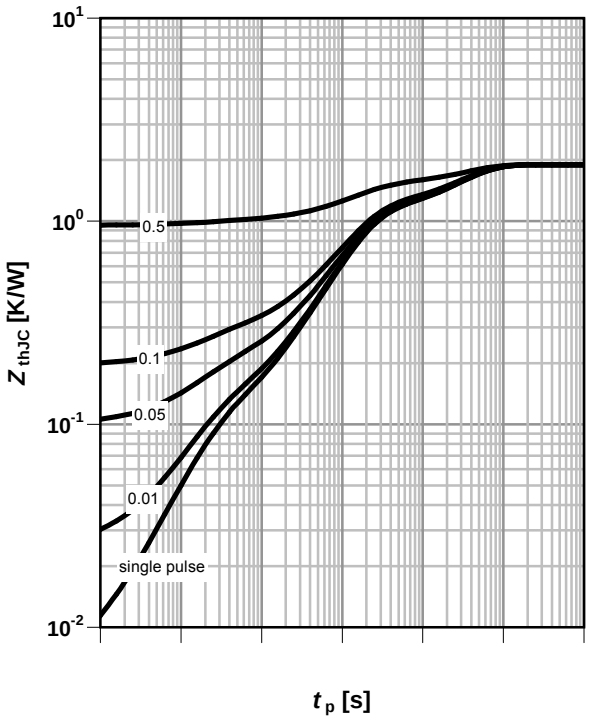
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

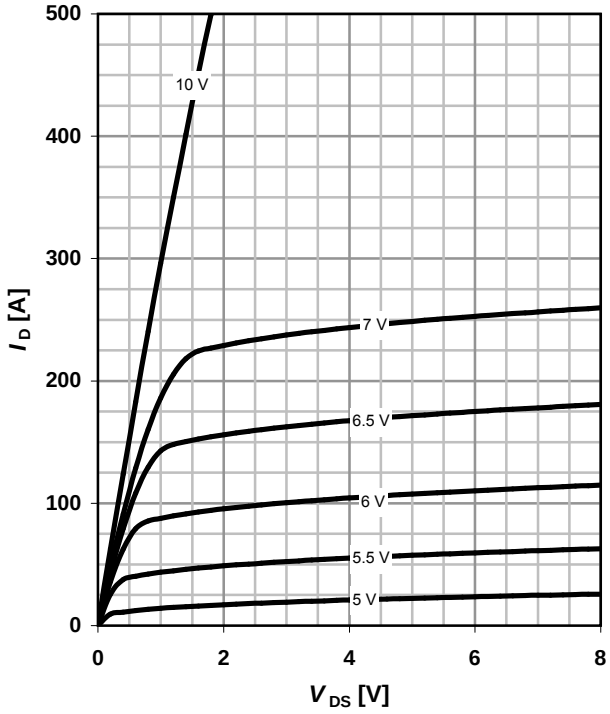
parameter: $D = t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25$ °C

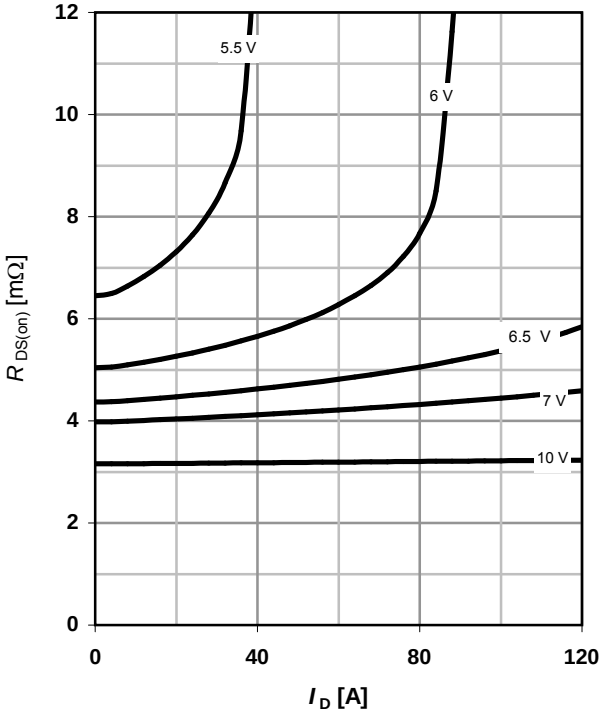
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = (I_D)$; $T_j = 25$ °C

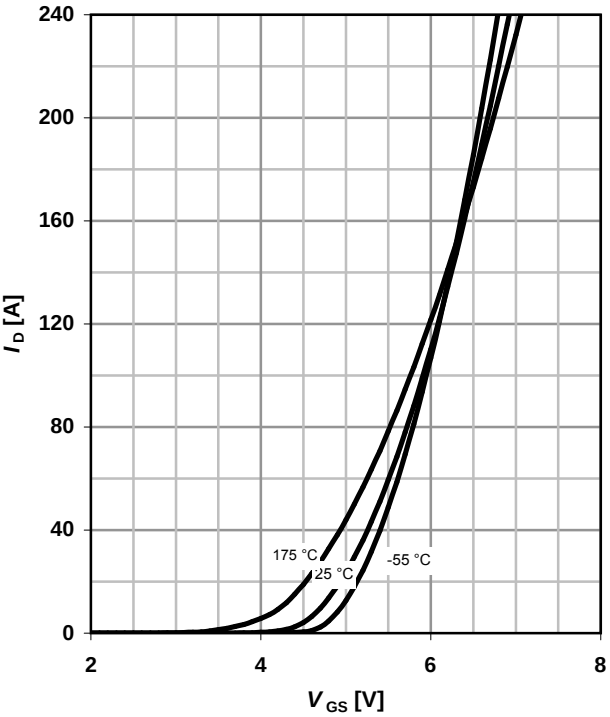
parameter: V_{GS}



7 Typ. transfer characteristics

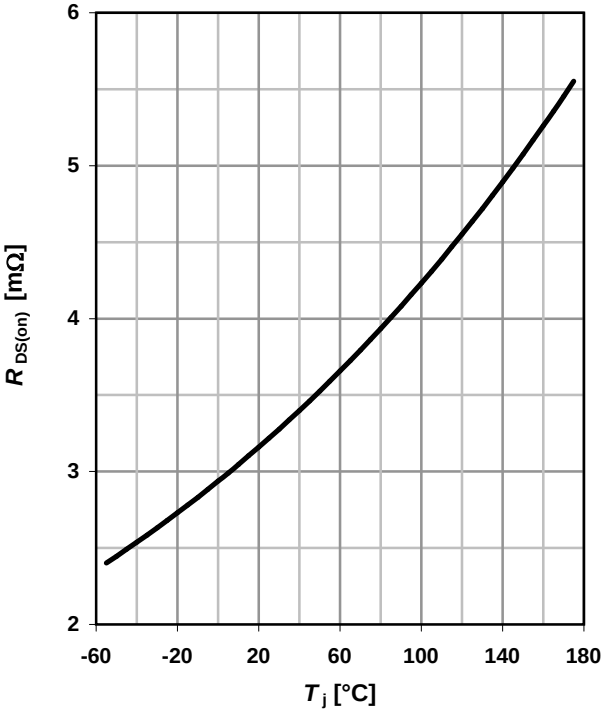
$I_D = f(V_{GS})$; $V_{DS} = 6$V

parameter: T_j



8 Typ. drain-source on-state resistance

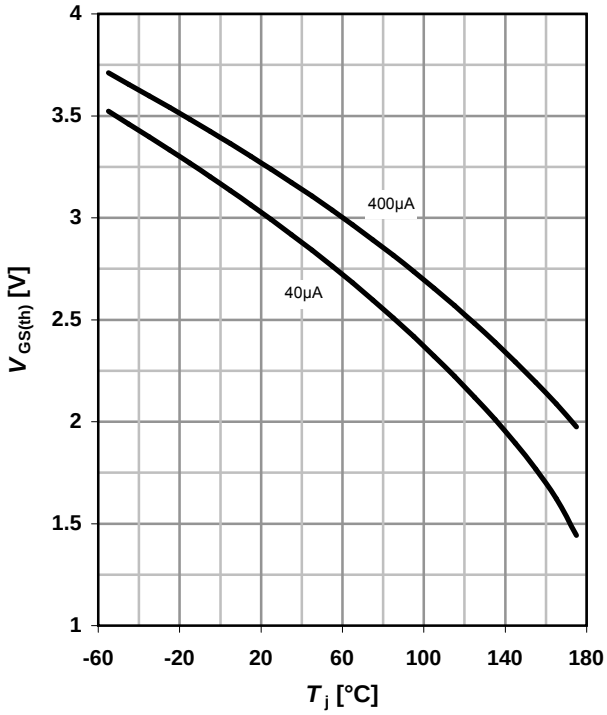
$R_{DS(on)} = f(T_j)$; $I_D = 100$ A; $V_{GS} = 10$ V



9 Typ. gate threshold voltage

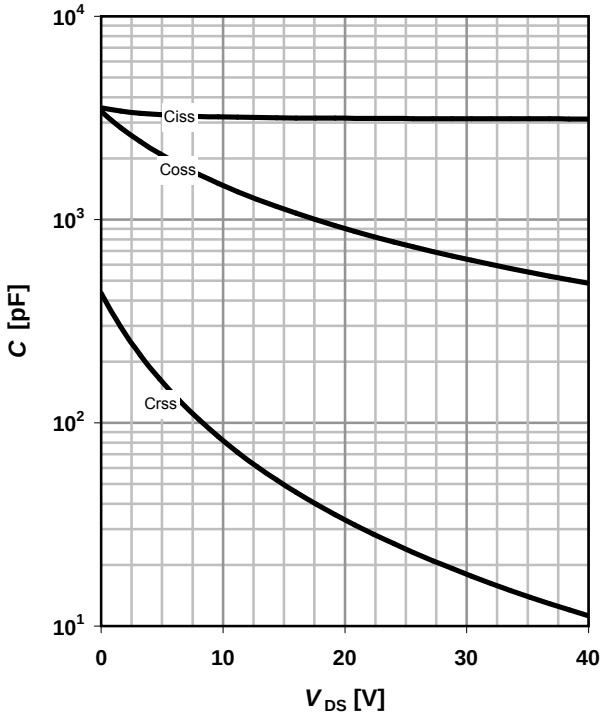
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

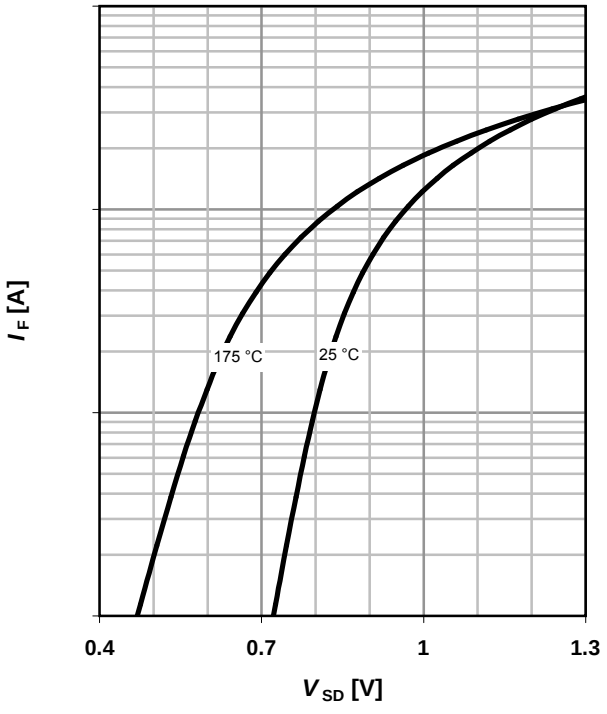
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz



11 Typical forward diode characteristicis

IF = f(V_{SD})

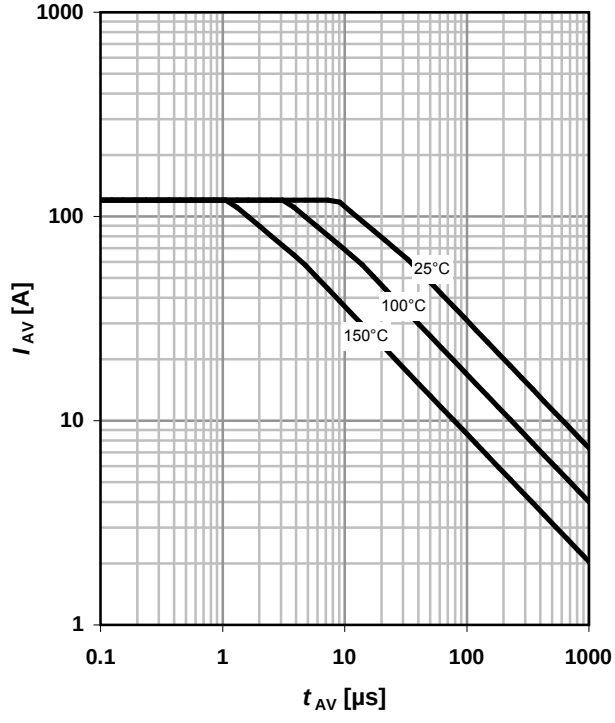
parameter: T_j



12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$

parameter: $T_{j(start)}$



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Revision History

Version	Date	Changes
1.0	22.10.2013	Final Datasheet
1.1	07.04.2014	Added Avalanche Current

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